

## HIGH VOLTAGE FAST-SWITCHING NPN POWER TRANSISTOR

PRELIMINARY DATA

- HIGH VOLTAGE CAPABILITY
- LOW SPREAD OF DYNAMIC PARAMETERS
- MINIMUM LOT-TO-LOT SPREAD FOR RELIABLE OPERATION
- VERY HIGH SWITCHING SPEED

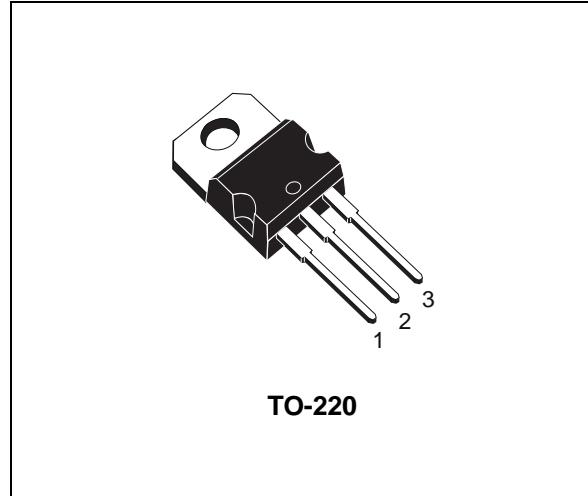
### APPLICATIONS

- FOUR LAMP ELECTRONIC BALLAST FOR:  
120 V MAINS IN PUSH-PULL  
CONFIGURATION;  
277 V MAINS IN HALF BRIDGE CURRENT  
FEED CONFIGURATION.

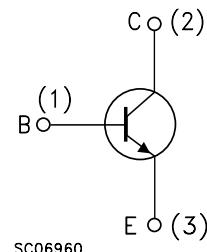
### DESCRIPTION

The device is manufactured using high voltage Multi Epitaxial Planar technology for high switching speeds and high voltage capability. It uses a Cellular Emitter structure with planar edge termination to enhance switching speeds while maintaining a wide RBSOA.

Thanks to an increased intermediate layer, it has an intrinsic ruggedness which enables the transistor to withstand a high collector current level during Breakdown condition, without using the transil protection usually necessary in typical converters for lamp ballast.



### INTERNAL SCHEMATIC DIAGRAM



### ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
$V_{CES}$	Collector-Emitter Voltage ( $V_{BE} = 0$ )	1100	V
$V_{CEO}$	Collector-Emitter Voltage ( $I_B = 0$ )	450	V
$V_{EBO}$	Emitter-Base Voltage ( $I_C = 0$ )	12	V
$I_C$	Collector Current	4	A
$I_{CM}$	Collector Peak Current ( $t_p < 5 \text{ ms}$ )	8	A
$I_B$	Base Current	2	A
$I_{BM}$	Base Peak Current ( $t_p < 5 \text{ ms}$ )	4	A
$P_{tot}$	Total Dissipation at $T_c = 25^\circ\text{C}$	70	W
$T_{stg}$	Storage Temperature	-65 to 150	°C
$T_j$	Max. Operating Junction Temperature	150	°C

## BUL1102E

### THERMAL DATA

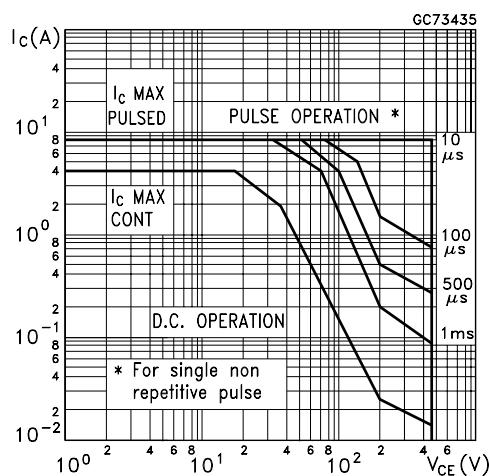
R <sub>thj-case</sub>	Thermal Resistance Junction-Case	Max	1.78	°C/W
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ELECTRICAL CHARACTERISTICS ( $T_{case} = 25^{\circ}\text{C}$  unless otherwise specified)

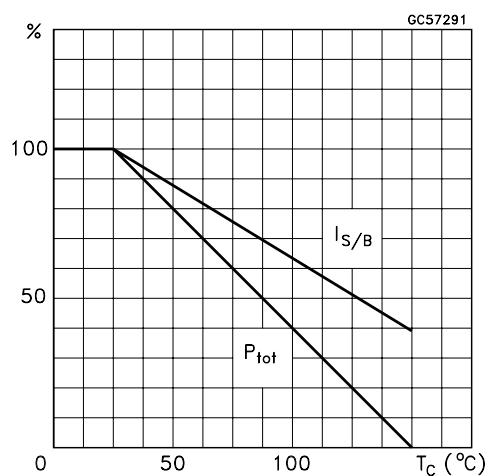
Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
I <sub>CES</sub>	Collector Cut-off Current ( $V_{BE} = 0$ )	$V_{CE} = 1100 \text{ V}$				100	μA
I <sub>EBO</sub>	Emitter Cut-off Current ( $I_B = 0$ )	$V_{EB} = 12 \text{ V}$				1	mA
V <sub>CEO(sus)*</sub>	Collector-Emitter Sustaining Voltage ( $I_B = 0$ )	$I_C = 100 \text{ mA}$		450			V
V <sub>CE(sat)*</sub>	Collector-Emitter Saturation Voltage	$I_C = 2 \text{ A}$	$I_B = 400 \text{ mA}$			1.5	V
V <sub>BE(sat)*</sub>	Base-Emitter Saturation Voltage	$I_C = 2 \text{ A}$	$I_B = 400 \text{ mA}$			1.5	V
$h_{FE}^*$	DC Current Gain	$I_C = 250 \text{ mA}$ $I_C = 2 \text{ A}$	$V_{CE} = 5 \text{ V}$ $V_{CE} = 5 \text{ V}$	35 10		70 20	
t <sub>s</sub> t <sub>f</sub>	RESISTIVE LOAD Storage Time Fall Time	$I_C = 2.5 \text{ A}$ $I_{B1} = 0.5 \text{ A}$ $T_P = 30 \mu\text{s}$	$V_{CC} = 250 \text{ V}$ $I_{B2} = 1 \text{ A}$ (see figure 2)			2.5 300	μs ns
E <sub>sb</sub>	Avalanche Energy	$L = 2 \text{ mH}$ $I_{BR} \leq 2.5 \text{ A}$ (see figure 1)	$C = 1.8 \text{ nF}$ $25^{\circ}\text{C} < T_C < 125^{\circ}\text{C}$	6			mJ

\* Pulsed: Pulse duration = 300 μs, duty cycle 1.5 %

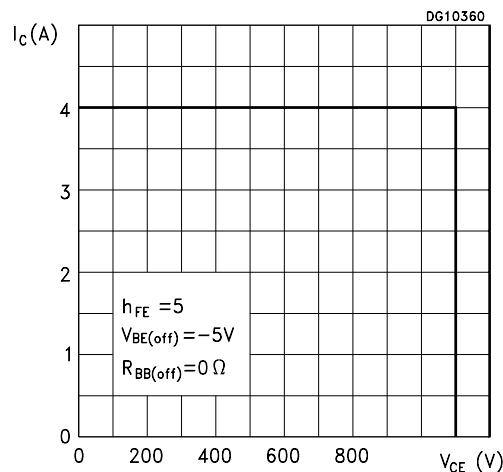
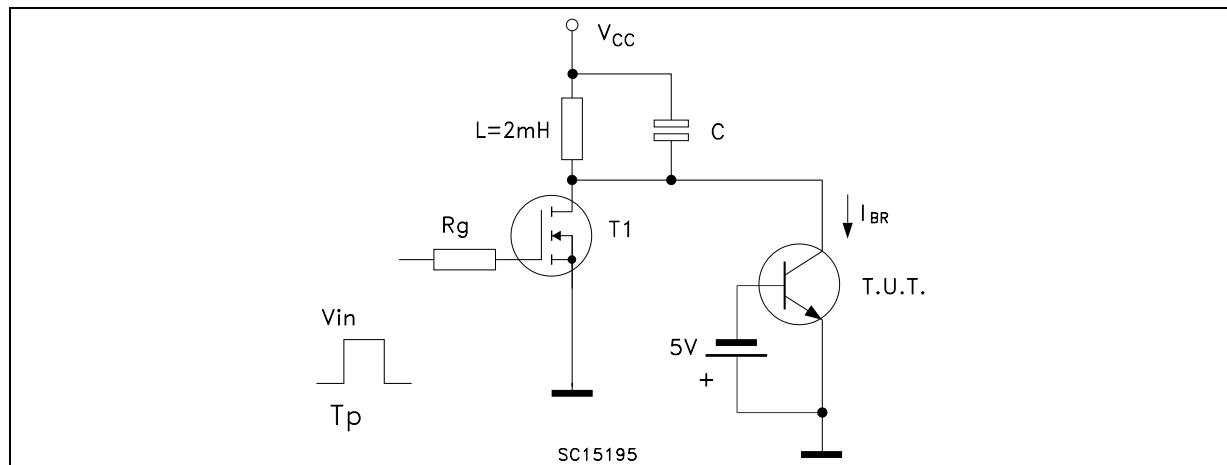
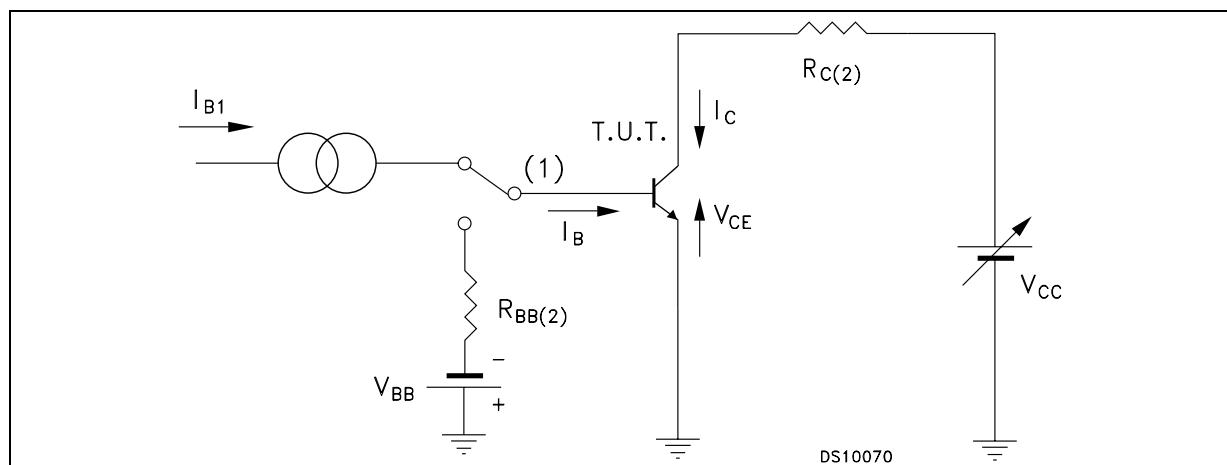
Safe Operating Areas



Derating Curve

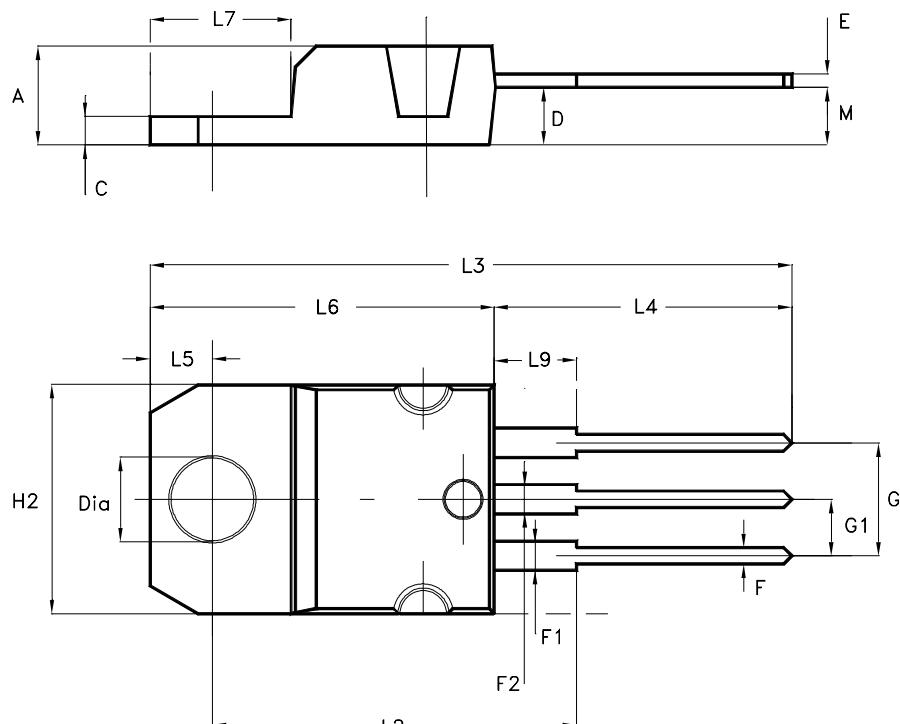


## Reverse Biased SOA

**Figure 1:** Energy Rating Test Circuit**Figure 2:** Resistive Load Switching Test Circuit

## TO-220 MECHANICAL DATA

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	4.40		4.60	0.173		0.181
C	1.23		1.32	0.048		0.052
D	2.40		2.72	0.094		0.107
E	0.49		0.70	0.019		0.027
F	0.61		0.88	0.024		0.034
F1	1.14		1.70	0.044		0.067
F2	1.14		1.70	0.044		0.067
G	4.95		5.15	0.194		0.202
G1	2.40		2.70	0.094		0.106
H2	10.00		10.40	0.394		0.409
L2		16.40			0.645	
L4	13.00		14.00	0.511		0.551
L5	2.65		2.95	0.104		0.116
L6	15.25		15.75	0.600		0.620
L7	6.20		6.60	0.244		0.260
L9	3.50		3.93	0.137		0.154
M		2.60			0.102	
DIA.	3.75		3.85	0.147		0.151



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